



Material Content Data Sheet



Sales Product Name		IPD70N10S3L-12		Issued		4. July 2019		
MA#		MA003596994						
Package		PG-TO252-3-11		Weight*		373.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.833	1.56	1.56	15620	15620
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		577	
	non noble metal	copper	7440-50-8	215.017	57.57	57.65	575771	576521
	non noble metal	aluminium	7429-90-5	4.526	1.21	1.21	12119	12119
wire	non noble metal	aluminium	7429-90-5	4.526	1.21	1.21	12119	12119
encapsulation	organic material	carbon black	1333-86-4	1.200	0.32		3213	
	plastics	epoxy resin	-	21.000	5.62		56235	
	inorganic material	silicondioxide	60676-86-0	97.801	26.19	32.13	261892	321340
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10015	10015
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.095	0.03		254	
	noble metal	silver	7440-22-4	0.119	0.03		318	
	non noble metal	lead	7439-92-1	4.537	1.22	1.28	12150	12722
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51353	51419
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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